

Abstract of the Disclosure

A TV-BGA package comprises: a PCB having bonding fingers; an adhesive material being coated on an edge of the PCB; a sealing post being adhered on the adhesive material; a semiconductor testing chip having a plurality of bonding pads adhered on the PCB; a plurality of metal wires separately connecting bonding pads of the PCB to the bonding fingers of the PCB; a sealing cap adhered on a sealing post for sealing the semiconductor chip; and a plurality of solder balls adhered to a lower side of the PCB. An extrusion is formed at a upper end of the sealing post, and the sealing cap is adhered on the extrusion of the sealing post. Further, the sealing cap is adhered on the extrusion of the sealing post by a low temperature thermoplastic tape or a material similar to low temperature thermoplastic tape. In the TV-BGA package, a sealing post is adhered on the adhesive material coated on an edge of the PCB, and then a sealing cap is capped on the sealing post, so that a test vehicle is manufactured. Therefore, the TV-BGA package can be easily manufactured and is suitable to test high density and speed elements.